



Product Change Notice

Micron PCN: 30839
 Date: 3/1/2013

Type of Change:	Manufacturing Process Change	
Title of Change:	Broad Market e•MMC IT BGA 100b Firmware and Manufacturing Changes	
Description of Change:	Broad Market e•MMC IT BGA 100b products will be manufactured with the following changes: <ul style="list-style-type: none"> • Polyimide die coating (new passivation layer) on the NAND die (L74A/L73A) will improve manufacturability of multi-die packages. • New controller version, PS8200FF, will improve the power-on circuit's margin at < -30°C. • New Firmware. • New substrate design will improve signal integrity. • BGA 100-ball assembly site will change from SPIL to AMKOR Korea. 	
Reason for Change:	Optimization of Manufacturing Efficiency and Product Enhancement	
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Product Affected: Broad Market e•MMC 100-ball 4GB (J54K), 8GB (J55U), 16GB (J56V), 32GB (J57V)

Affected Micron Part Numbers	Replacement Part Numbers
N2M400FDB311A3CE	MTFC4GLDDQ-4M IT
N2M400FDB311A3CF	MTFC4GLDDQ-4M IT
N2M400GDB321A3CE	MTFC8GLDDQ-4M IT
N2M400GDB321A3CF	MTFC8GLDDQ-4M IT
N2M400HDB321A3CE	MTFC16GJDDQ-4M IT
N2M400HDB321A3CF	MTFC16GJDDQ-4M IT
N2M400JDB341A3CE	MTFC32GJDDQ-4M IT
N2M400JDB341A3CF	MTFC32GJDDQ-4M IT

Method of Identification:	<ul style="list-style-type: none"> • Part Numbers change (see table above) • New PRV field in CID register change from "3.x" to "4.x" will identify new controller and firmware version.
Micron Sites Affected:	Fabrication – FAB2 (Lehi, UT, US), FAB6 (Manassas, VA, US), FAB10 (Singapore) Assembly – Subcontractor

Product/Data Availability

New Production:

Sample Availability: May 2013
Qual Data Availability: May 2013
Production Shipments: June 2013

(Continued on next page.)

Note: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change



Old Production:

Last Time Buy: Dec 2013
Last Time Ship: June 2014

Qualification Plan: Product manufactured with the changes described above will be qualified according to Company qualification procedure and best practices. Qualification plan will be available upon request.

Orders placed prior to the LTB date are subject to current inventory levels, which may vary based on market conditions and customer demand. Early orders are encouraged.